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|-----------------------------------|---------------------------------------|--|-------------|
| Notice of References Cited | Application/Control No. 10/773,727 | Applicant(s)/Patent Under Reexamination NING, XIAN JIE | |
| | Examiner Toniae M. Thomas | Art Unit 2822 | Page 1 of 1 |

U.S. PATENT DOCUMENTS

| * | | Document Number Country Code-Number-Kind Code | Date MM-YYYY | Name | Classification |
|---|---|--|-----------------|---------------|----------------|
| | A | US-2003/0073282 | 04-2003 | Ning, Xian J. | 438/243 |
| | B | US-6,451,667 B1 | 09-2002 | Ning, Xian J. | 438/397 |
| | C | US-6,559,004 B1 | 05-2003 | Yang et al. | 438/253 |
| | D | US-6,593,185 B1 | 07-2003 | Tsai et al. | 438/253 |
| | E | US-6,620,701 B2 | 09-2003 | Ning, Xian J. | 438/396 |
| | F | US-6,638,830 B1 | 10-2003 | Tsai et al. | 438/397 |
| | G | US-6,706,588 B1 | 03-2004 | Ning, Xian J. | 438/250 |
| | H | US-6,765,255 B2 | 07-2004 | Jin et al. | 257/301 |
| | I | US- | | | |
| | J | US- | | | |
| | K | US- | | | |
| | L | US- | | | |
| | M | US- | | | |

FOREIGN PATENT DOCUMENTS

| * | | Document Number Country Code-Number-Kind Code | Date MM-YYYY | Country | Name | Classification |
|---|---|--|-----------------|---------|------|----------------|
| | N | DE 102 47 454 A1 | 10-2001 | Germany | Ning | H01L 21/822 |
| | O | | | | | |
| | P | | | | | |
| | Q | | | | | |
| | R | | | | | |
| | S | | | | | |
| | T | | | | | |

NON-PATENT DOCUMENTS

| * | | Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages) |
|---|---|--|
| | U | Wolf, Ph.D., Stangley, Richard N. Tauber, Ph.D., "Dry Etching for VLSI Fabrication," Silicon Processing for the VLSI Era - Vol. 1: Process Technology, Lattice Press, 1986, pages 546-550. |
| | V | |
| | W | |
| | X | |

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.